

REMARKS

Applicant respectfully requests consideration of the present application as amended. Claims 1-19 are canceled without prejudice. New claims 54-73 have been added. The new claims are fully disclosed and supported in the original specification and no new matter has been added.

Title

Applicant has amended the title of the invention to more accurately reflect the invention as claimed in the present application.

Specification

Applicant submits herein proposed amendments to correct informalities. These amendments add no new matter.

Conclusion

Applicant submits that the presented claims are in condition for allowance and respectfully requests that the Examiner pass the claims to allowance. The Examiner is respectfully invited to contact Brent Vecchia at (303) 740-1980 if the Examiner finds any impediment to the prompt allowance of these claims that could be clarified with a telephone conference.

Charge our Deposit Account

Please charge any shortage to our Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Date: October 26, 2001


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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Title:

The Title has been amended as follows,

[Application of Pressure Sensitive Adhesive (PSA) to Pre-Attach Thermal Interface Film/Tape To Cooling Device]

Adhesive To Attach A Cooling Device To A Thermal Interface

In the Specification:

The following has been added to the first sentence of the Specification:

This application is a continuation patent application of Application Serial No. 09/158,227, entitled *Application of Pressure Sensitive Adhesive (PSA) to Pre-attach Thermal Interface Film/Tape to Cooling Device*, and filed on September 22, 1998.

The paragraph beginning at page 9, line 24 has been amended as follows:

Next, thermal interface 102, with PSA strips 104 applied near edges [118] thereof, is attached to a surface 104 of base plate 120 as illustrated in **Figure 5**. The attachment is mainly due to an adhesive surface of PSA 104 that makes contact with surface 140 of base plate 120. Note that PSA 104 is compliable, becoming very thin when thermal interface 102 is pressed and attached to base plate 120 of heat sink 118. Heat may be transferred from the integrated circuit package 116 to the heat sink 118 mainly via heat transfer area 106, demarcated by dotted lines 112 and 114. Heat transfer area 106 is not covered by PSA 104. The vendor of the heat sink may then ship the assembly, including the heat sink 118 with the thermal interface 102 attached thereto, to the manufacturer of

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the integrated circuit package, for further assembling the integrated circuit package 116 to the assembly.

In the claims:

Claims 1-19 are cancelled.

Claims 54-73 are new.

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